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**Polprevodniški elementi - Metode za mehansko in klimatsko preskušanje - 42. del:  
Shranjevanje pri določeni temperaturi in vlažnosti (IEC 60749-42:2014)**

Semiconductor devices - Mechanical and climatic test methods - Part 42: Temperature  
humidity storage

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**iTeh STANDARD PREVIEW**

Dispositifs à semiconducteurs - (Méthodes d'essais mécaniques et climatiques - Partie  
42: Stockage - Température et humidité

[SIST EN 60749-42:2014](https://standards.iteh.ai/catalog/standards/sist/ef25950c-c880-433f-8e8b-1c69174500ad/sist-en-60749-42-2014)

**Ta slovenski standard je istoveten z: EN 60749-42:2014**

**ICS:**

19.060	Mehansko preskušanje	Mechanical testing
31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general

**SIST EN 60749-42:2014****en**

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EUROPEAN STANDARD  
NORME EUROPÉENNE  
EUROPÄISCHE NORM

**EN 60749-42**

October 2014

ICS 31.080.01

English Version

**Semiconductor devices - Mechanical and climatic test methods -  
Part 42: Temperature and humidity storage  
(IEC 60749-42:2014)**

Dispositifs à semiconducteurs - Méthodes d'essais  
mécaniques et climatiques - Partie 42: Stockage de  
température et d'humidité  
(CEI 60749-42:2014)

Halbleiterbauelemente - Mechanische und klimatische  
Prüfverfahren - Teil 42: Lagerung bei Wärme und Feuchte  
(IEC 60749-42:2014)

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Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels**

## Foreword

The text of document 47/2200/FDIS, future edition 1 of IEC 60749-42, prepared by IEC/TC 47 "Semiconductor devices." was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60749-42:2014.

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60749-20	-	Semiconductor devices - Mechanical and climatic test methods -- Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat	EN 60749-20	-

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IEC 60749-42

Edition 1.0 2014-08

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Semiconductor devices – Mechanical and climatic test methods –  
Part 42: Temperature and humidity storage**

**Dispositifs à semiconducteurs – Méthodes d'essais mécaniques et climatiques –  
Partie 42: Stockage de température et d'humidité**

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## CONTENTS

FOREWORD.....	3
1 Scope.....	5
2 Normative references .....	5
3 Test equipment.....	5
3.1 Capacity of the equipment .....	5
3.2 Materials and construction of the thermostatic/humidistatic chamber .....	5
3.3 Water to be used in the test .....	5
4 Procedure.....	5
4.1 Preconditioning.....	5
4.2 Initial measurements.....	6
4.3 Tests .....	6
4.3.1 Inserting and removing specimens.....	6
4.3.2 Test conditions .....	6
4.3.3 Test duration .....	6
4.3.4 Post treatment.....	7
4.3.5 End-point measurement.....	7
5 Failure criteria .....	7
6 Information to be given in applicable procurement document.....	8
Figure 1 – Unsaturated pressurized vapour test conditions profile.....	7
Table 1 – Temperature and humidity storage test conditions.....	6

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**SEMICONDUCTOR DEVICES –  
MECHANICAL AND CLIMATIC TEST METHODS –****Part 42: Temperature and humidity storage**

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